

FQT3P20TF-VB Datasheet P-Channel 200V (D-S)MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (∧)	I _D (A)	Q _g (Typ.)		
- 200	$0.8 \text{ at V}_{GS} = -10 \text{ V}$	- 2.0	8.0		
	0.9 at $V_{GS} = -6.0 \text{ V}$	- 1.8	0.0		

FEATURES

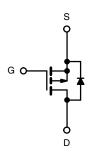
- Halogen-free According to IEC 61249-2-21 Available
- Trench Power MOSFET
- · Ultra Low On-Resistance
- Small Size



APPLICATIONS

• Active Clamp Circuits in DC/DC Power Supplies





P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted						
Parameter		Symbol	5 s	Steady State	Unit	
Drain-Source Voltage		V _{DS}	- 200		V	
Gate-Source Voltage		V _{GS}	± 20			
Continuous Drain Current (T _{.J} = 150 °C) ^{a, b}	T _A = 25 °C	- I _D	- 2.0	- 1.68		
Continuous Drain Current (1 _J = 150 °C) ^{cc}	T _A = 70 °C		- 1.8	- 1.56		
Pulsed Drain Current		I _{DM}	- 5.8		Α	
Continuous Source Current (Diode Conduction) ^{a, b}		I _S	- 1.0	- 0.6		
Single Pulse Avalanche Current	L = 1.0 mH	I _{AS}	4.0 1.2			
Single Pulse Avalanche Energy		E _{AS}			mJ	
Mariana Barra Birair ating a h	T _A = 25 °C	P _D	1.45	0.95	W	
Maximum Power Dissipation ^{a, b}	T _A = 70 °C		0.8	0.48	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Marrian de Ambienta	t ≤ 5 s	R _{thJA}	75	100	°C/W	
Maximum Junction-to-Ambient ^a	Steady State		120	166		
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	40	50		

Notes:

- a. Surface Mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.



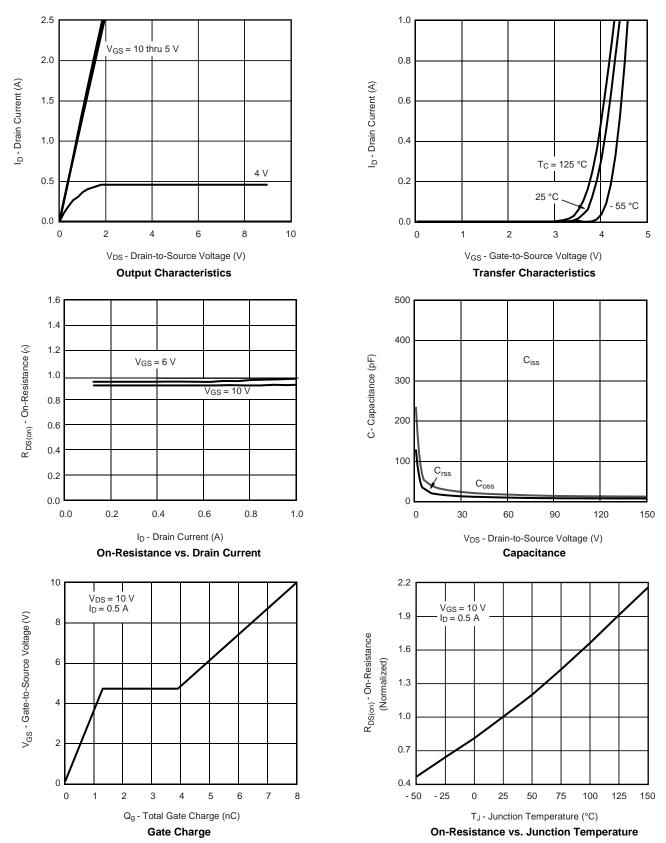
			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 200			V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 2.5		- 4.5	v	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nΑ	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 200 V, V _{GS} = 0 V			- 1	μA	
		V _{DS} = - 200 V, V _{GS} = 0 V, T _J = 55 °C			- 10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -15 \text{ V}, V_{GS} = 10 \text{ V}$	- 1.0			Α	
	D	$V_{GS} = -10 \text{ V}, I_D = -0.5 \text{ A}$		0.80		^	
Drain-Source On-Resistance ^a	R _{DS(on)}	$V_{GS} = -6.0 \text{ V}, I_D = -0.5 \text{ A}$		0.90			
Forward Transconductance ^a	9 _{fs}	$V_{DS} = -15 \text{ V}, I_{D} = -0.5 \text{ A}$		1.8		S	
Diode Forward Voltage	V _{SD}	$I_S = -1.0 \text{ A}, V_{GS} = 0 \text{ V}$		- 0.85	- 1.2	V	
Dynamic ^b			•				
Total Gate Charge	Qg	V 400 V V 40 V		8.0	12	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = -100 \text{ V}, V_{GS} = 10 \text{ V}$ $I_{D} \cong -0.5 \text{ A}$		1.3			
Gate-Drain Charge	Q _{gd}	.0 = 0.0		2.5			
Gate Resistance	R_g	f = 1.0 MHz		8.0		^	
Input Capacitance	C _{iss}			370	510		
Output Capacitance	C _{oss}	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		28		pF	
Reverse Transfer Capacitance	C _{rss}			16			
Switching ^c							
Turn-On Time	t _{d(on)}	V 400 V D 400		8	12		
Tuiti-Ott Tillie	t _r	$V_{DD} = -100 \text{ V}, R_L = 100 \land I_D \cong -1.0 \text{ A}, V_{GEN} = -10 \text{ V}$		11	17	ns	
Turn-Off Time	t _{d(off)}	$R_q = 6 \wedge$		16	25		
Tuiti-Oii Time	t _f	э		11	17		
Body Diode Reverse Recovery Charge	Q_{rr}	$I_F = 0.5 \text{ A}, dI/dt = 100 \text{ A/µs}$		140	200	nC	

- a. Pulse test: PW \leq 300 μ s duty cycle \leq 2 %. b. For DESIGN AID ONLY, not subject to production testing. c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

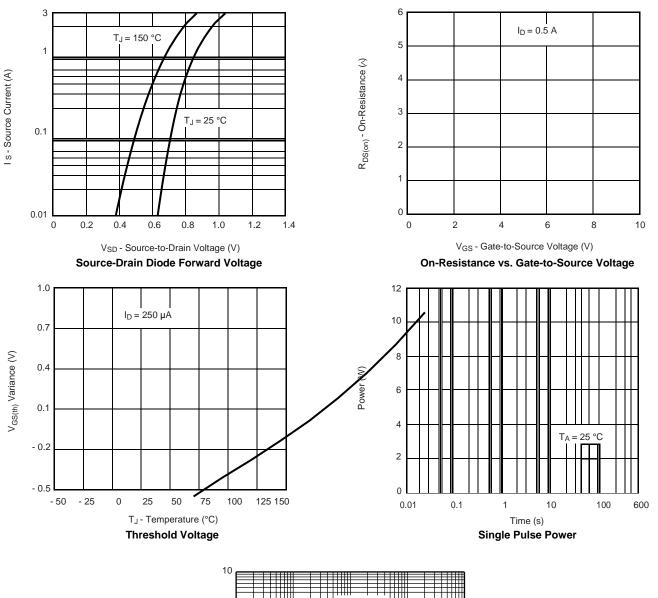


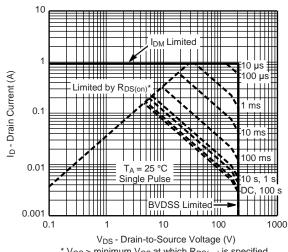
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





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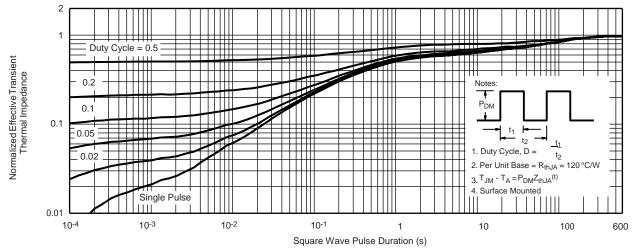


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



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